
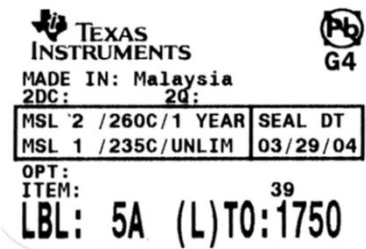



PCN Number:	20240507000.1	PCN Date:	May 08, 2024
Title:	Qualification of new Process Technology, Die Revision and Assembly BOM options for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	August 06, 2024	Sample requests accepted until:	June 07, 2024*
*Sample requests received after June 07, 2024 will not be supported.			
Change Type:			
<input type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process	
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Material	
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/> Wafer Fab Process	
PCN Details			
Description of Change:			
Texas Instruments is pleased to announce the qualification of a new process technology, die revision and Assembly BOM option for selected devices as listed below in the product affected section. Devices will remain at existing assembly sites:			
	Current	Proposed	
Wafer Fab	RFAB	RFAB	
Wafer Process technology	LBC7	LBC9	
The die was also changed as a result of the process change.			
Material differences:			
	Current	Proposed	
Mount compound	4208458	4224264	
Mold compound	4205443	4211649	
Marking	<div style="border: 1px solid black; padding: 5px; text-align: center;"> DRV8848 \TI/ YMSG4 LLLL O </div> <div style="margin-top: 10px;"> \TI/ = TI LOGO YM = YEAR/MONTH DATE CODE S = ASSLY SITE CODE O = PIN 1 TI logo </div>	<div style="border: 1px solid black; padding: 5px; text-align: center;"> DRV8848 TI YMSG4 LLLL (CAV) </div> <div style="margin-top: 10px;"> \TI/ = TI LOGO YM = YEAR/MONTH DATE CODE S = ASSLY SITE CODE (CAV) = CAVITY NUMBER O = PIN 1 TI Letter, Mold cavity ID </div>	
The product datasheet(s) is being updated as summarized below.			
The following change history provides further details.			
		DRV8848 <small>SLLSEL7B OCTOBER 2014 – REVISED APRIL 2024</small>	
Changes from Revision A (November 2015) to Revision B (April 2024)		Page	
<ul style="list-style-type: none"> Corrected t_F and t_{RT} to denote fall time and rise time respectively..... 		4	
Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
DRV8848	SLLSEL7A	SLLSEL7B	http://www.ti.com/product/DRV8848
Qual details are provided in the Qual Data Section.			
Reason for Change:			

Continuity of Supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Impact on Environmental Ratings:					
<p>Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.</p>					
RoHS	REACH	Green Status	IEC 62474		
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change		
Changes to product identification resulting from this PCN:					
<p>Die Rev:</p> <table style="width: 100%;"> <tr> <td style="width: 50%;">Current Die Rev [2P] A</td> <td style="width: 50%;">New Die Rev [2P] A</td> </tr> </table>				Current Die Rev [2P] A	New Die Rev [2P] A
Current Die Rev [2P] A	New Die Rev [2P] A				
<p>Sample product shipping label (not actual product label):</p> <div style="display: flex; align-items: flex-start;"> <div style="flex: 1;">  <p>TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750</p> </div> <div style="flex: 1; text-align: center;">  </div> <div style="flex: 2;"> <p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CC0: USA (22L) AS0: MLA (23L) AC0: MYS</p> </div> </div>					
Product Affected:					
DRV8848LPWPR		DRV8848PWPR			

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV8848PWPR	QBS Reference: PDRV8912QPWPRQ1	QBS Reference: PDRV8410PWPR	QBS Reference: TPS54525PWPR	QBS Reference: DRV8847PWPR
HAST	A2	Biased HAST	130C	96 Hours	-	3/231/0	-	-	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/231/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	1/77/0	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	3/90/0	3/90/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	3/90/0	3/90/0

Type	#	Test Name	Condition	Duration	Qual Device: DRV8848PWPR	QBS Reference: PDRV8912QPWPRQ1	QBS Reference: PDRV8410PWPR	QBS Reference: TPS54525PWPR	QBS Reference: DRV8847PWPR
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	3/132/0	3/132/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	3/15/0	3/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	1/30/0	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-	-

- QBS: Qual By Similarity
- Qual Device DRV8848PWPR is qualified at MSL3 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2303-044

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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